

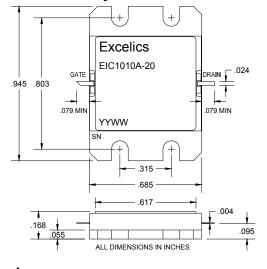
EIC1010A-20

ISSUED 07/03/2007

10.00-10.25 GHz 20-Watt Internally Matched Power FET

FEATURES

- 10.00- 10.25GHz Bandwidth •
- Input/Output Impedance Matched to 50 Ohms
- +42.5 dBm Output Power at 1dB Compression •
- 6.0 dB Power Gain at 1dB Compression •
- 27% Power Added Efficiency
- Hermetic Metal Flange Package .
- 100% Tested for DC, RF, and R_{TH}



Caution! ESD sensitive device.

SYMBOL	PARAMETERS/TEST CONDITIONS ¹	MIN	TYP	MAX	UNITS
P _{1dB}	Output Power at 1dB Compressionf = 10.00-10.25GHz V_{DS} = 9 V, $I_{DSQ} \approx 4000$ mA	41.5	42.5		dBm
G _{1dB}	Gain at 1dB Compression $f = 10.00-10.25GHz$ $V_{DS} = 9 \text{ V}, I_{DSQ} \approx 4000 \text{mA}$	5.5	6.5		dB
∆G	Gain Flatnessf = 10.00-10.25GHz V_{DS} = 9 V, $I_{DSQ} \approx 4000$ mA			±0.5	dB
PAE	Power Added Efficiency at 1dB Compression V_{DS} = 9 V, $I_{DSQ} \approx 4000$ mAf = 10.00-10.25GHz		27		%
\mathbf{Id}_{1dB}	Drain Current at 1dB Compression f = 10.00-10.25GHz		5500	6500	mA
I _{DSS}	Saturated Drain Current V_{DS} = 3 V, V_{GS} = 0 V		14000	18000	mA
VP	Pinch-off Voltage V_{DS} = 3 V, I_{DS} = 140 mA		-2.5	-4.0	V
R _{TH}	Thermal Resistance ²		1.4	1.6	°C/W

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MAXIMUM RATING (Case Temperature 25 °C)

SYMBOL	CHARACTERISTIC	ABSOLUTE ¹	CONTINUOUS ²
V _{DS}	Drain to Source Voltage	15V	10 V
V _{GS}	Gate to Source Voltage	-5V	-3.0 V
I _{DS}	Drain Current	I _{DSS}	9400mA
I _{GSF}	Forward Gate Current	3000mA	500 mA
P _{IN}	Input Power	42.5 dBm	@ 3dB compression
PT	Total Power Dissipation	110W	94 W
T _{CH}	Channel Temperature	175°C	175°C
T _{STG}	Storage Temperature	-65°C ~ 175°C	-65°C ~ 175°C

xceeding any of the above ratings may result in permanent damage.

2. Exceeding any of the above ratings may reduce MTTF below design goals.

Specifications are subject to change without notice. Excelics Semiconductor, Inc. 310 De Guigne Drive, Sunnyvale, CA 94085 Phone: 408-737-1711 Fax: 408-737-1868 Web: www.excelics.com

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness